

L Number	Hits	Search Text	DB	Time stamp
1	100205	(slot slit gap groove) with (pad paddle heat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 11:04
2	285726	(pad paddle heat) with (opening slit slot via grooves slots holes)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 11:05
3	35080	(semiconductor die chip ic (integrated adj circuit)) same ((pad paddle heat) with (opening slit slot via grooves slots holes))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 11:07
4	204	((semiconductor die chip ic (integrated adj circuit)) same ((pad paddle heat) with (opening slit slot via grooves slots holes))) same (tiebar dambar ((dam tie) adj3 bar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 11:08
5	171	(leadframe lead (lead adj frame)) same (((semiconductor die chip ic (integrated adj circuit)) same ((pad paddle heat) with (opening slit slot via grooves slots holes))) same (tiebar dambar ((dam tie) adj3 bar)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 11:09



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Records for: PN=US 6281568

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Records 1-2 of 2 In long Format

☐ 1. 2/34/1 (Item 1 from file: 351)

013054409 \*\*Image available\*\*

WPI Acc No: 2000-226274/200020

Thin plastic integrated circuit package for power or analog semiconductor devices has a die pad surrounded by leads from a leadframe and encapsulated leaving upper and lower surfaces of leads and die exposed

Patent Assignee: AMKOR TECHNOLOGY INC (AMKO-N); ANAM SEMICONDUCTOR INC (ANAM-N); ANAM SEMICONDUCTOR TECHNOLOGY CO LTD (ANAM-N); AMKOR TECHNOLOGY (AMKO-N)

Inventor: GLENN T P; JEWLER S J; MOON D H; ROMAN D; YEE J H; LEE J H

Number of Countries: 029 Number of Patents: 006

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
EP 989608	A2	20000329	EP 99305775	A	19990721	200020 B
JP 2000150765	A	20000530	JP 99325884	A	19991012	200033
KR 2000028854	A	20000525	KR 9942950	A	19991005	200110
US 6281568	B1	20010828	US 98176614	A	19981021	200151
TW 429570	A	20010411	TW 99116602	A	19990928	200157
US 6455356	B1	20020924	US 98176614	A	19981021	200266
			US 99395875	A	19990914	

Priority Applications (No Type Date): US 98176614 A 19981021; US 99395875 A 19990914

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
EP 989608	A2	E	25	H01L-023/495	

Designated States (Regional): AL AT BE CH CY DE DK ES FI FR GB GR IE IT LI LT LU LV MC MK NL PT RO SE SI

JP 2000150765 A 19 H01L-023/50

KR 2000028854 A H01L-023/50

US 6281568 B1 H01L-023/12

TW 429570 A H01L-023/495

US 6455356 B1 H01L-021/48

Div ex application US 98176614

Div ex patent US 6281568

Abstract (Basic): EP 989608 A2

NOVELTY - The package comprises a planar metal die pad (22) with an integrated circuit formed on a first side. Contact pads on the die are wire bonded to a number of leads (30). The package body is formed from an encapsulant material which covers the sides of the die pad and leads leaving the top and underside exposed.

DETAILED DESCRIPTION - INDEPENDENT CLAIMS are also included for the following:

(a) a metal leadframe for making an encapsulated integrated circuit package;

(b) a patterned metal strip for making a number of encapsulated integrated circuit packages;

(c) a method of making a package for an integrated circuit device.

USE - Packaging for an integrated circuit.

ADVANTAGE - Has numerous uses for e.g. power and analog devices in

a small size package. Leads can be placed closer to the die to minimize the length of the bond wire. The exposed second surface of the die pad can be connected by solder to the printed circuit board for package cooling.

DESCRIPTION OF DRAWING(S) - The figure shows a plan view of the leadframe used for making the package.

Metal die pad (22)

Leads (30)

pp; 25 DwgNo 2/16

Derwent Class: U11

International Patent Class (Main): H01L-021/48; H01L-023/12; H01L-023/495; H01L-023/50

International Patent Class (Additional): H01L-023/28

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□ 2.

2/34/2 (Item 2 from file: 345)

15806842

Basic Patent (No,Kind,Date): EP 989608 A2 20000329

PATENT FAMILY:

EUROPEAN PATENT OFFICE (EP)

Patent (No,Kind,Date): EP 989608 A2 20000329

PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE AND METHOD OF MAKING THE SAME  
(English; French; German)

Patent Assignee: AMKOR TECHNOLOGY INC (US); ANAM SEMICONDUCTOR INC (KR)

Author (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); MOON D H (KR); ROMAN DAVID (US); YEE J H (KR)

Priority (No,Kind,Date): US 176614 A 19981021

Applic (No,Kind,Date): EP 99305775 A 19990721

Designated States: (National) AT; BE; CH; CY; DE; DK; ES; FI; FR; GB; GR; IE; IT; LI; LU; MC; NL; PT; SE

IPC: \* H01L-023/495

Derwent WPI Acc No: \* G 00-226274; G 00-226274

Language of Document: English

Patent (No,Kind,Date): EP 989608 A3 20010110

PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE AND METHOD OF MAKING THE SAME  
(English; French; German)

Patent Assignee: AMKOR TECHNOLOGY INC (US); ANAM SEMICONDUCTOR INC (KR)

Author (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); MOON D H (KR); ROMAN DAVID (US); YEE J H (KR)

Priority (No,Kind,Date): US 176614 A 19981021

Applic (No,Kind,Date): EP 99305775 A 19990721

Designated States: (National) AT; BE; CH; CY; DE; DK; ES; FI; FR; GB; GR; IE; IT; LI; LU; MC; NL; PT; SE

IPC: \* H01L-023/495

Derwent WPI Acc No: \* G 00-226274

Language of Document: English

JAPAN (JP)

Patent (No,Kind,Date): JP 2000150765 A2 20000530

SEMICONDUCTOR INTEGRATED CIRCUIT PLASTIC PACKAGE, ULTRA- COMPACT LEAD FRAME FOR MANUFACTURE THEREOF, AND ITS MANUFACTURE (English)

Patent Assignee: AMKOR TECHNOLOGY INC; ANAM SEMICONDUCTOR INC

Author (Inventor): GLENN THOMAS P; JEWLER SCOTT J; ROMAN DAVID; YEE J H; D H MUN

Priority (No,Kind,Date): US 176614 A 19981021

Applic (No,Kind,Date): JP 99325884 A 19991012

IPC: \* H01L-023/50; H01L-023/12; H01L-023/28

Derwent WPI Acc No: \* G 00-226274  
Language of Document: Japanese

## KOREA, REPUBLIC (KR)

Patent (No,Kind,Date): KR 2000028854 A 20000525  
PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE, MICRO LEAD FRAME AND  
PRODUCING METHOD OF PACKAGE (English)  
Patent Assignee: AMKOR TECHNOLOGY KOREA INC; AMKOR ELECTRONICS INC  
Author (Inventor): GLEN THOMAS P (KR); JEWELLER SCOTT J (KR); ROMAN  
DAVID (KR); LEE JAE HAK (KR); MUN DU WHAN (KR)  
Priority (No,Kind,Date): US 176614 A 19981021  
Applic (No,Kind,Date): KR 9942950 A 19991005  
IPC: \* H01L-023/50  
Derwent WPI Acc No: \* G 00-226274  
Language of Document: Korean

## UNITED STATES OF AMERICA (US)

Patent (No,Kind,Date): US 6281568 BA 20010828  
PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE AND LEADFRAME HAVING  
PARTIALLY UNDERCUT LEADS AND DIE PAD (English)  
Patent Assignee: AMKOR TECHNOLOGY INC (US); ANAM SEMICONDUCTOR INC  
(US)  
Author (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); ROMAN  
DAVID (US); YEE J H (KR); MOON D H (KR)  
Priority (No,Kind,Date): US 176614 A 19981021  
Applic (No,Kind,Date): US 176614 A 19981021  
National class: \* 257684000; 257666000; 257696000; 257698000;  
257796000; 257675000; 257712000; 257713000; 257707000; 257711000;  
257730000; 257788000  
IPC: \* H01L-023/12; H01L-023/28; H01L-023/50  
Derwent WPI Acc No: \* G 00-226274  
Language of Document: English  
Patent (No,Kind,Date): US 6455356 BA 20020924  
METHODS FOR MODING A LEADFRAME IN PLASTIC INTEGRATED CIRCUIT DEVICES  
(English)  
Patent Assignee: AMKOR TECHNOLOGY (US)  
Author (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); ROMAN  
DAVID (US); YEE J H (KR); MOON D H (KR)  
Priority (No,Kind,Date): US 395875 A 19990914; US 176614 A3  
19981021  
Applic (No,Kind,Date): US 395875 A 19990914  
Addnl Info: 6281568 Patented  
National class: \* 438123000; 438124000; 438127000; 029827000;  
029841000; 029855000  
IPC: \* H01L-021/48  
Derwent WPI Acc No: \* G 00-226274  
Language of Document: English

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